



Metals Testing Company

News Release

Tech Brief for Ultrasonic Bond Testing Shadow Variations now available from MTC

Have you ever heard about the use of a backwall shadow technique in ultrasonic (UT) inspection of production parts? An informative article (a.k.a., Tech Brief) is now available from Metals Testing Company that describes the pitfalls of using such an inspection method. Specifically, the Tech Brief details how such a UT inspection can overcall a minimum sized defect in a bond line test of even thin walled materials. The example is clearly illustrated using C-Scan images and related RF waveforms. A copy of the Tech Brief is now available as a pdf file in the Literature section of MTC's website at www.mtc62.com.



MTC, located in South Windsor, CT (USA) provides NDT laboratory inspection services to various markets ranging from aerospace to automotive industries. Their in-house capabilities include immersion and contact ultrasonics (UT), chemical etch and etch anodizing, fluorescent penetrant inspection (FPI), and magnetic particle inspection (MPI). With regard to aircraft engine manufacturers, MTC is one of the few approved independent laboratories in the world for providing Blue Etch Anodize (BEA) inspections.

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